

## Product Change Notification - KSRA-30TQUS060

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**Date:**

10 Sep 2018

**Product Category:**

32-bit Microcontrollers

**Affected CPNs:****Notification subject:**

CCB 3519 Initial Notice: Qualification of MTAI as an additional assembly site for selected Atmel products available in 32L TQFP (7x7x1mm) package using gold (Au) bond wire

**Notification text:****PCN Status:**

Initial notification.

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

**NOTE:** For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**

Qualification of MTAI as an additional assembly site for selected Atmel products available in 32L TQFP (7x7x1mm) package using gold (Au) bond wire

**Pre Change:**

Assembled in ASCL assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900 die attach, and C194 lead frame material

**Post Change:**

Assembled in ASCL assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900 die attach, and C194 lead frame material.

Assembled in MTAI assembly site using gold (Au) bond wire, 3280 die attach, and C7025 lead frame material.

### Pre and Post Change Summary:

|                           | Pre Change                | Post Change               |                                                  |
|---------------------------|---------------------------|---------------------------|--------------------------------------------------|
| Assembly Site             | ASE Group Chung-Li / ASCL | ASE Group Chung-Li / ASCL | Microchip Technology Thailand<br><br>(HQ) / MTAI |
| Wire material             | CuPdAu                    | CuPdAu                    | Au                                               |
| Die attach material       | EN-4900                   | EN-4900                   | 3280                                             |
| Molding compound material | G700                      | G700                      | G700                                             |
| Lead frame material       | C194                      | C194                      | C7025                                            |

**Impacts to Data Sheet:**

None

**Change Impact:**

None

## Reason for Change:

To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

October 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

### Time Table Summary:

[illegible]

|                         |  |  |  |  |  |  |  |   |  |  |
|-------------------------|--|--|--|--|--|--|--|---|--|--|
| Availability            |  |  |  |  |  |  |  |   |  |  |
| Final PCN<br>Issue Date |  |  |  |  |  |  |  | X |  |  |

#### Method to Identify Change:

Traceability code

#### Qualification Plan:

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

#### Revision History:

**September 10, 2018:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### Attachment(s):

[PCN\\_KSRA-30TQUS060\\_Qual\\_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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